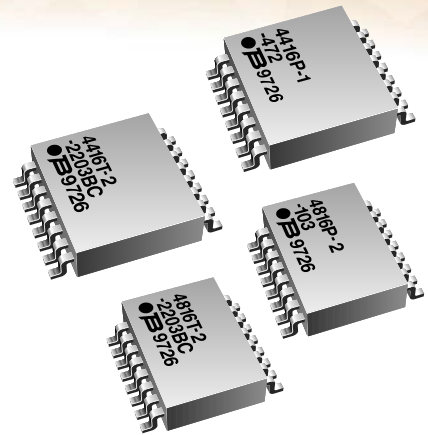


# Product Change Notification

August, 2007

Bourns Manufacturers Representatives  
Corporate Distributor Product Managers  
Americas Sales Team  
Asia Sales Team  
Europe Sales Team  
Bourns Internal  
Bourns Plant Managers



## Surface Mount Networks Model Series 4400 & 4800 Terminal Finish Material Change

Effective with shipments beginning October 1, 2007 (date code C0740), we are making a running change to the terminal finish on the surface mount Resistor Network Model Series [4400P](#), [4800P](#), [4400T](#) and [4800T](#). The finish is applied after molding and forming of the terminals.

Currently the hot solder dip process uses a 96.5 % Sn 3 % Ag 0.5 % Cu alloy.

The new hot solder dip process will use a 99.3 % Sn 0.7 % Cu alloy.

*Both alloys are backwards compatible with SnPb soldering processes.*

As a result of the alloy change, the labeling on our RoHS page on our website and on the shipping label will also change in accordance with the industry “JEDEC STANDARD JESD97: Marking, Symbols and Labels for Identification of Lead (Pb) Free Assemblies, Components, and Devices”.

Terminal finish code:

Current marking: e1 – SnAgCu

After the change: e2 – Sn alloys with no Bi or Zn excluding SnAgCu

Note: All of the product in any package will contain the same finish process and will have the same “e” value applied.